

2801

PATENT APPLICATION

**RESPONSE UNDER 37 CFR §1.116
EXPEDITED PROCEDURE
TECHNOLOGY CENTER ART UNIT 2814**

DO NOT REMOVE
6-7-01

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Akihiko MURATA

Application No.: 09/245,288

Filed: February 5, 1999

For: SEMICONDUCTOR APPARATUS SUBSTRATE, SEMICONDUCTOR
APPARATUS, AND METHOD OF MANUFACTURING THEREOF AND
ELECTRONIC APPARATUS

Group Art Unit: 2814

Examiner: D. Graybill

Docket No.: 101937

#12/C
6-2-01
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TECHNOLOGY CENTER 2814

AMENDMENT AFTER FINAL REJECTION UNDER 37 CFR §1.116

Director of the U.S. Patent and Trademark Office
Washington, D.C. 20231

Sir:

In reply to the Office Action mailed March 1, 2001, please amend the above-identified application as follows:

IN THE CLAIMS:

Please replace claims 1 and 7 as follows:

- Sub
C/DIT
1. (Amended) A semiconductor apparatus, comprising:
a substrate main body having a delineated mounting surface for mounting the semiconductor device;
a plurality of leads formed on the mounting surface, the plurality of leads radially extending from a peripheral area toward a central area of the substrate main body;
and